1. Number 1		Search Text soler add ball improve with wire with bond and 25%/s.cols.	DB USPAT; US-PGPUE;	Time stamp 2002/10/21 08:25
		and 25 /8 .0018.	EPO; JPO; DERWENT; IBM TDB	
<u>:</u>		soler adj ball with improve with wire with bond	USPAT; US-PGPUE; EPO; UPO; DERWENT;	2002/10/21 08:28
3	;	solder adj ball with improve with wire with bind	IBM_TOB USPAT; US-PGPUB; EP0; JF0; DERWENT;	2002/10/21 08:30
4	g g	solder adj ball with wire with bond with connection	IBM TDB	2001/10/21 08:38
r	24	solder adj ball with wire with bond with lead	IBM TDB	2002/10/21 08:39
-	803	(257/691).CCLs.	DEFWENT; IEM_TDE US:AT; US-PGPUE; EEC; JEG;	2002/10/19 16:23
-	223	((257/691).CCLS.) and power with line	DEFWENT; IEM_TOE USFAT; US-PGFUE; EF0; JFO; DEFWENT;	2002/10/17 18:17
-	219530	{{257/691}.CCLS.} and metallization with over coat	IEM_TDB USTAT; US-PGPUB; EB1; UPO;	2002/10/17 18:18
-	2	((257/691).CCLS.) and metallization with overcoat	DEFWENT; IBM_TOB USFAT; US-PGPUB; EPD; CPC; DEFWENT;	.2002/10/17 18:19
-	19	({257/691}.CCLS.) and metallization with (die IC semiconductor chip) with surface	IBM_TDB US!AT; US-PGPUE; EPD; UPO; DERWENT;	2002/10/17 18:44
- - -	5	8311259.URPN. 5751257.URPN. ."5223639" "5250940" "5252953" "5252954" : "5286999" "5311056" "5358304" : "5359224" "5365113" : "5394008" : "5428247" ; "5442233" :		2002/10/17 18:23 2002/10/17 18:25 2002/10/17 18:26
-	51	"5461255" "5473190").PN. 5461255.URPN. 257 227 .OCLS.	USPAT USPAT; US-FSFUH; EFG; JFU; DERWENT;	2002/10/17 18:32 2002/10/17 19:47
-	13	.,25%-20%.CCLS." and metallization with die TC semiconductor chip* with surface	IBM_TOB USPAT; US-PGPUB; EFG; JFG; CERWENT; IBM_TOB	2002)10/17 15:47

_ ~	59 1257/2087.CCLS.	USPAT; US-PGPUE; EPG; JPO;	2002/10/17 18:4%
_	6 257/208).OOLS. and metallization with	DEFWENT; IBM_TDB USFAT;	2002, 10/17 18:47
	die IC semiconductor chip/ with surface	US-PGPUE; EPO; JPO; DEFWENT; IBM TOB	
_	27 4249192.URPM.	USFĀT	2602/19/17 18:49
- 42	65 257 (ଶ୍ରେଷ	USFAT; US-PGPUE; EFF; UFC; DEFWENT; IEM TOE	2002/10/18 10:48
- 3ତି	66 .25"/6+6).CCLS.	US:ĀT; US-PGPUE; EFH; JFC; EEFWENT; IBM TUB	2002,10/18/10:48
- 13	59 ((257/666).CCLS.) AND(metallization lead line bus 7 WITH (chip die ic semiconductor integrated adj circuit)WITH surface	USFĀT;	20011.10 18 10:52
- 8	42 (((.57.5665).CCLS.) AND(metallization lead line b.s - WITH (chip die ic semiconductor integrated adj circuit)WITH surface) AND wire AND lead	USFĀT;	2002/10/18 10:52
_ 7	96 ((157,666).CCLS.) AND(metallization lead line bus - WITH (chip die ic semiconductor integrated adj circuit)WITH surface) and wire WITH lead	USFAT; US-PGFUE; EST; JEC; DERWENT; IBM TIB	mcom, 10 18 10:53
-	30 ((25%7666).CCLS.) AND(metallization lead line bus + WITH (chip die ic semiconductor integrated adj circuit)WITH surface) and wire WITH lead) AND active WITH element	uspār;	2600,710 18 11:04
-	8 "5148064" "5150828" "5205463" "5710407" "5717252" "5803246" "58 2336" "5898225").PN.	USFAT	2002/10 18 10:55
-	13 "4156362": "4862245": "4946754" "51'1711" "5252853" "5331200" "5334467" "5538920" "5565379" "5569944" ! "5578526" "5587336" "5677567").PN.	USPAT	2002 10/18 10:59
=	14 539449 .URPN.	USFAT	
- 1	55 ((35 %66).CCLS.) AND(metallization lead line bus \ WITH (chip die ic semiconductor integrated adj circuit)WITH surface) and wire WITH lead) AND encapsulate	US-PGPUB;	2002'10'18 11:35
-	7 ("5167183" "5429248" "5834837" "5893216" "5977613" "5998877" "6323715").PN.	us: Āt	2002/10/18 11:08
-	1 "4546374".PN.	USTAT	2002/10/18 11:12
-	11 4546371.URPN.	TABRU	2002/10/18 11:12
-	29 5302849.0BEN. -4 "4719500" "8574297" "5640024"	USHAT USHAT	2002/10/19 11:34 2002/10/18 11:41
	#5777331#1.EX.	Q	
-	0 6144100.pm.	USPAT; US PGPUB; EFD; JFO; DERWENT; IBM_TOB	0005x10x18 13888

-		ēlatēlupa.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	1332/13/14 13:64
			IBM_TDB	
_		"8666084"	USPAT	2102/10/18 13:58
-		word with line with power with ground		2002/10/18 14:63
			US-PGPUB; EPG; JPG; DERWENT; IBM TOB	
-		word with line with power with ground. AND LET-8.COLE.	USPĀT; US-PGPUB; EFO; JPO; DERWENT; IEM TDB	2002/10/18 14:53
-		6066515.URPN.	USFĀT	2002/10/18 18:29
-		("5148964" "5150828" "5205463" "5710457" "5717252" "5803246" "5872338" "5898225").PN.	USPAT	2002/10/18 18:37
_		257/691 . COLS.	USPAT;	2002,10.18 18:39
			U3-PGPUB; EFC; JPC; DEFWENT; IBM TDB	
-		((257/691).CCLS.) and power with lines with surface	US: AT; US-PGPUE; EEC; JPC; DEFWENT; IEM TDB	2002,10,18 18:52
	3	("5028983" _{("5256996" "5550406").PN.}	USFĀT	2002/10/18 18:43
	33	5677570.URPN. ("4355456" "4878098" "4916519" "4948754" "4949150" "4993305" "4993618" "5009721" "5061985" "5062801" "8226582" "5235212" "5319224" "5441917" "5463255" "5502337" "8523626" "8587607" "5602420" "5608245" "5642570" "5623154" "5637920" "5640048" "5641978" "5644166" "5652467" "5666008" "5677570" "5693984" "5712508" "5731634" "5742100").PN.	USEAT USEAT	2002/10/18 18:44 2002/10/18 18:47
-		(25 ⁿ /205).ddls.	USPAT; US-PGPUB; EP1; JPD; DEFWENT; IBM_TDB	2002/10/18 18:52
-	236	'28T.209'.CCLS.	USFAT; US-PGPUB; EP1; JP3; DEAWENT; IBM TDB	2002/10/18/19:52
-	* * *	.257/225 ¹ .2213." and power with lines with surface	US:ĀT; US-PGPUB; EP:; JPO; DERWENT; IBM TDB	2002/10/18 18:55
-		v257/209/.0018.7 and power with lines with surface	USPAT; US-FGFUB; EFP; JFC; DERWENT; IBM TOB	2002/10/18 19:55
-		.v.lb7.lv8'.0018. and power with line with surface	USPĀT; US-PGPUB; EFO; JEO; DERWENT; IBM_TOB	2000 1 14 18:56

-	3 66	197466 .COMS.	USPAT; US-PGPUB;	2002 10/1# 16:15
			EPC; JPC;	
			DEFWENT; IBM TDB	
-	13	*257/666 .0018. and power with line with	USFĀT;	2012/10/18 18:57
		surface	US-PGPUB; EPH; JPH;	
			DEFWENT;	
_	3.53	.257/666CClS., and line with surface	IBM_TDB US:AT;	2012/10/18 19:11
			US-PGPUE;	
			EF(; JPC; DEFWENT;	
			IE::_TDB US:AT;	
_	4.6%	power ground with line with surface and 157/\$.cols.	US:A.; US:PGPUB;	
			EFC; JPC;	
			DEFWENT; IBM TDB	
-	3.8	((power ground) with line with surface and 257/8.ccls.) and lead with frame	USFĀT; US-PGPUP;	2002/10/18 19:26
		257/5.CCIS./ and lead with frame	EFG; JPG;	
			DEFWENT; IBM TDB	
-	2	5973554.pn.	US!ĀT;	2662/10/21 08:22
			US-PGPUE; EFU; JPC;	
			DERWENT;	
		6144100.pn.	IBM_TDB USFAT;	2002/10/19 16:35
_	_	0144400.p	US-PGPUE;	2002/10/10 10.00
			EPO; CPC; DERWENT;	
			IBM TOB	
-	4	("5182420" "5367195" "5369220" "5734200"}.PN.	USI ĀT	2002/10/19 16:40
=	3.00	(251/666,.CCLS.	USTAT;	2002/10/19 17:53
			US-PGPUB; EP:; CFC;	
			DEFWENT;	
_	3	* [257/666].CCLS.' and art with lead with	IEM_TDE US:AT;	2002/10/19 18:13
		frame with mounting with pad	US-PGPUF; EPD; JPC;	
			DEFWENT;	
	5	conventionally with mounting with pad with	IBM_TDB USFAT;	2002/10/19 18:15
-	J	lead adj frame and (25%).ccls.	US-PGPUF;	
			EFD; JEC; DEFWENT;	
			IBM_TDB	
_	ć	conventionally with mounting with pad with lead adj frame	US:AT; US-PGPUB;	2002/10/19 18:16
		Tour Ga_ France	EPT; JFO;	
			DEFWENT; IBM TOB	
-	**	conventionally with die with pad with lead	US!ĀT;	2012/10/19 18:16
		adj frame	US-PGFUK; EF); JFO;	
			DERWENT;	
			IBM_TDB	